CHANGE NOTIFICATION

Linear Technology Corporation
1630 McCarthy Blvd., Milpitas, CA 95035-7417
(408) 432-1900

March 30, 2015

Dear Sir/Madam: PCN#033015

Subject: **Notification of Change to LTC6246, LTC6252, LTC6255 Die**

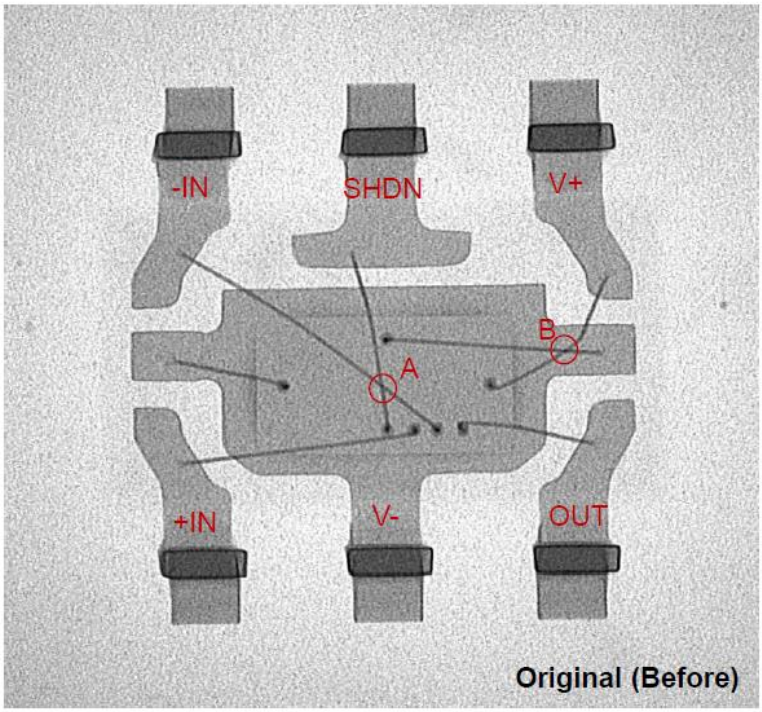
Please be advised that Linear Technology has made changes to the bond pad assignments of the LTC6246, LTC6252, and LTC6255 single op amps. This change is necessary due to the obsolescence of special insulated bond wire needed to support the original bond pad configuration. This insulated bond wire allowed bond wires to cross. The SHDN signal was reassigned to a different pad to avoid crossing bond wires. Another signal which previously connected to V- through a bond wire connection to the die paddle was connected on chip, eliminating the need for another bond wire. This change was qualified by performing characterization over the full operating temperature range and rigorous engineering evaluation across a broad range of application conditions. Summary of changes are attached below. As the pinout and performance are not affected, no changes have been made to the datasheet. The new revisions will be available with datecode of approximately 1534 and later.

Should you have any further questions or concerns please contact your local Linear Technology Sales person or you may contact me at 408-432-1900 ext. 2077, or by e-mail at JASON.HU@LINEAR.COM. If I do not hear from you by June 1, 2015, we will consider this change to be approved by your company.

Sincerely,

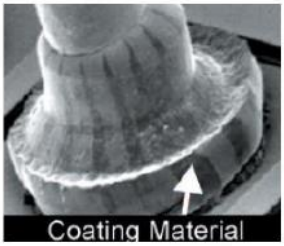
Jason Hu
Quality Assurance Engineer

LTC6246 X-wire layout (Before)



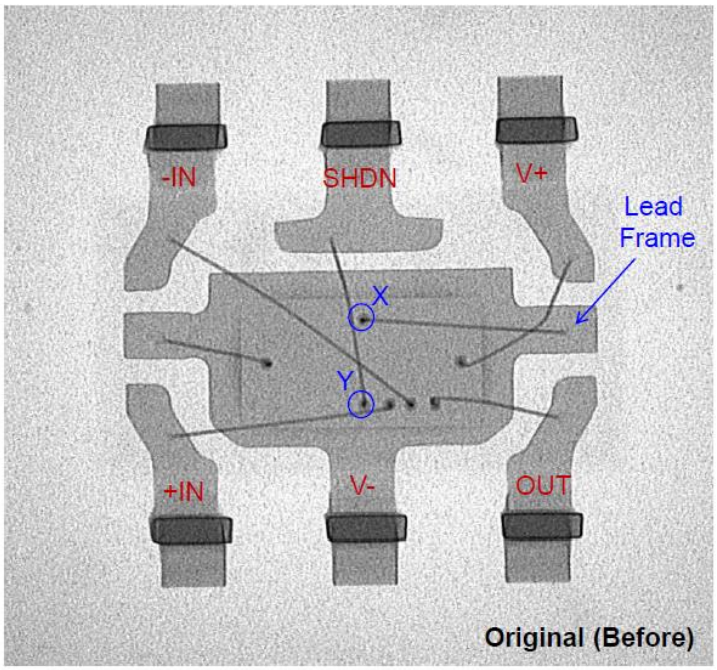
Insulated X-wire allowed wires to cross at points A and B.

Side View



Squashed Ball

Photos courtesy
Tanaka/ Microbonds

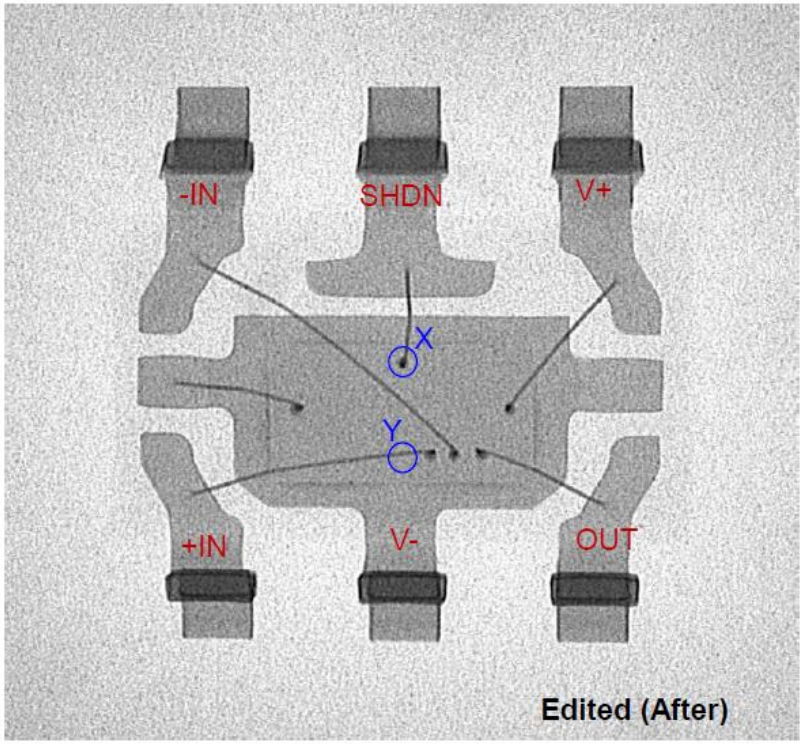


In the original design, the logic signal routed to pad X is connected to V- via a bond wire to the lead frame.

In the original design, the SHDN signal is routed to bond pad Y.

On-chip metal routing edits make it possible to change the bond pad X and Y assignments. This will eliminate the need for insulated bond wires.

LTC6246 layout (After)

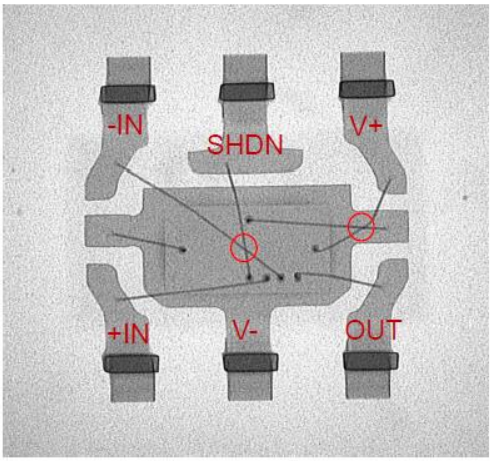


In the edited design, the logic signal previously routed to pad X is connected on-chip to V-. This eliminates the need for a bond wire from pad X to the paddle, allowing pad X to be wired differently, and reducing the bond wire count from 7 to 6 bond wires.

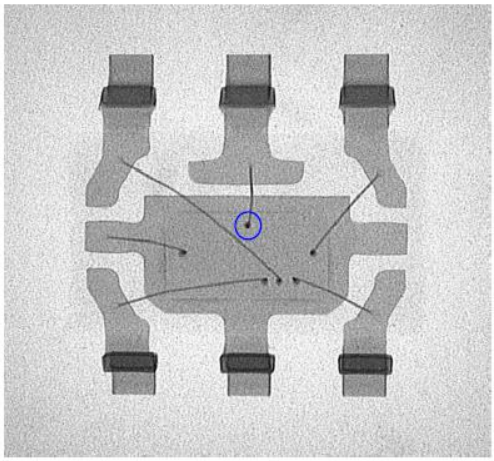
The SHDN signal is re-routed on-chip from bond pad Y to bond pad X. Pad X is wire bonded to SHDN pin rather than to the paddle.

Wire bond to pad Y is eliminated. Bond wires no longer cross, and the need for insulated bond wires is eliminated.

LTC6246 Before and After Summary

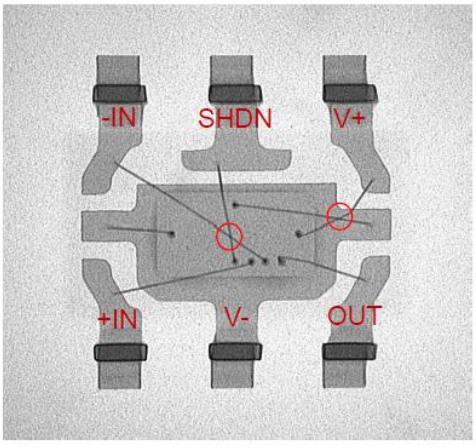


X-wire layout (Before)

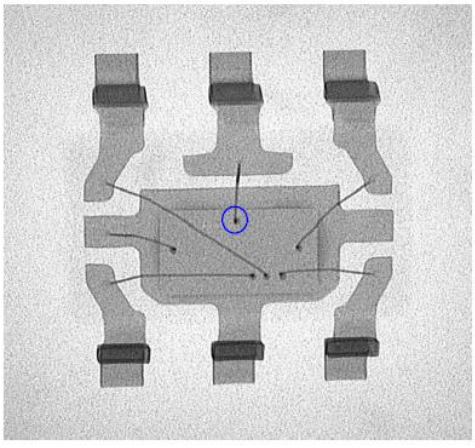


Standard-wire layout (After)

LTC6252 Before and After Summary



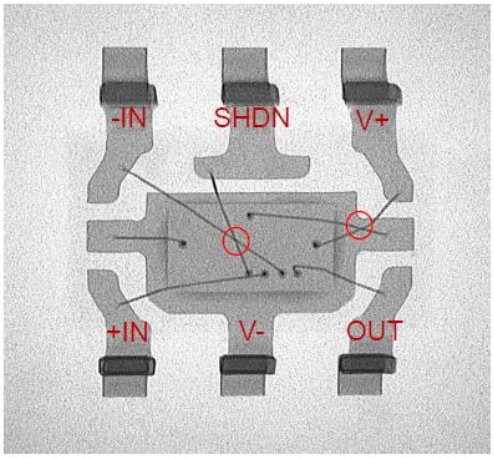
X-wire layout (Before)



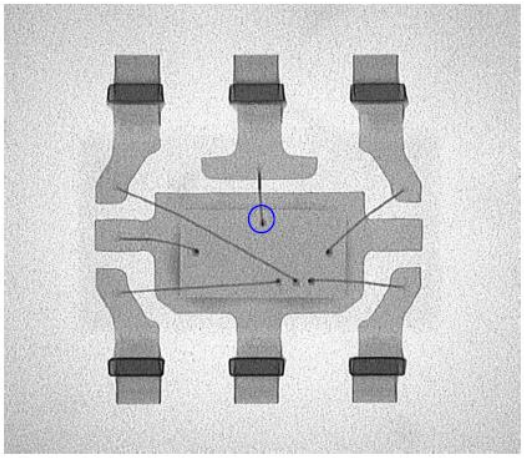
Standard-wire layout (After)

See LTC6246 for full explanation of changes.

LTC6255 Before and After Summary



X-wire layout (Before)



Standard-wire layout (After)

See LTC6246 for full explanation of changes.